

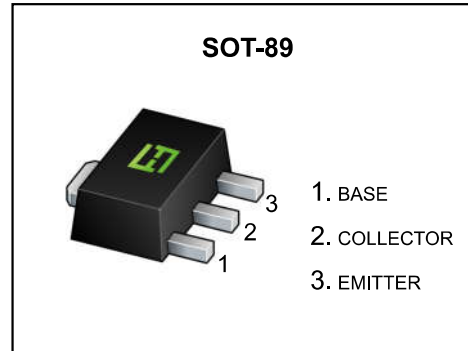
FEATURES

- PNP Complements to BCX51,BCX52,BCX53
- Low Voltage
- High Current

APPLICATIONS

- Driver Stages of Audio Amplifiers

MARKING: BCX54:BA, BCX54-10:BC, BCX54-16:BD
 BCX55:BE, BCX55-10:BG, BCX55-16:BM
 BCX56:BH, BCX56-10:BK, BCX56-16:BL



MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-Base Voltage	BCX54	45
		BCX55	60
		BCX56	100
V _{CEO}	Collector-Emitter Voltage	BCX54	45
		BCX55	60
		BCX56	80
V _{EBO}	Emitter-Base Voltage	5	V
I _C	Collector Current	1	A
I _B	Base Current	0.1	A
I _{BM}	Peak base Current (tp<1ms)	0.2	A
P _C	Collector Power Dissipation	500	mW
R _{θJA}	Thermal Resistance From Junction To Ambient	250	°C/W
T _J , T _{stg}	Operation Junction and Storage Temperature Range	-55~+150	°C
T _{opr}	Operation Temperature Range	-25~+125	°C

ELECTRICAL CHARACTERISTICS (Tamb=25°C unless otherwise specified)

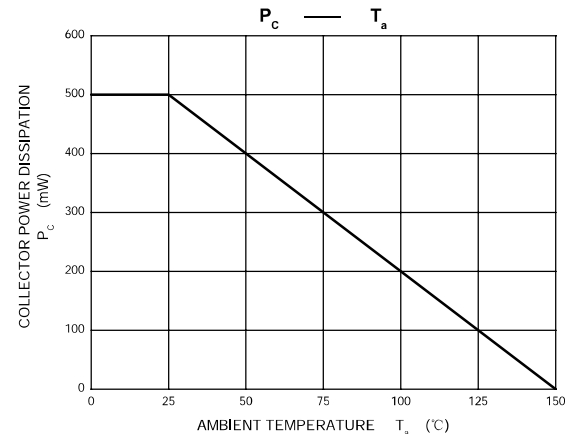
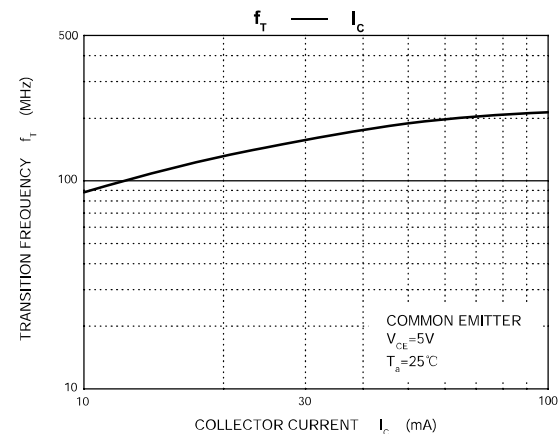
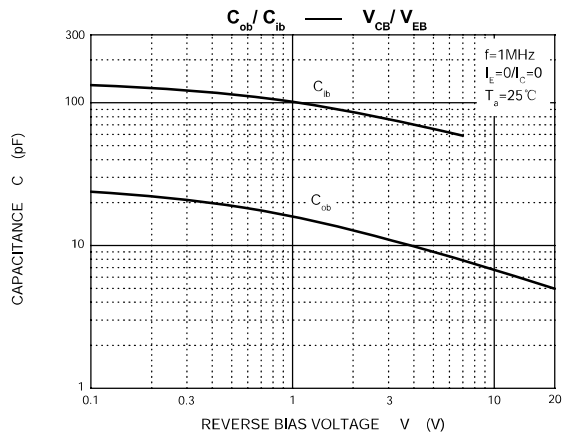
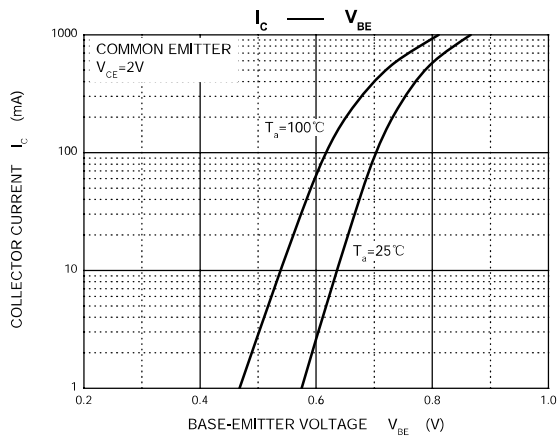
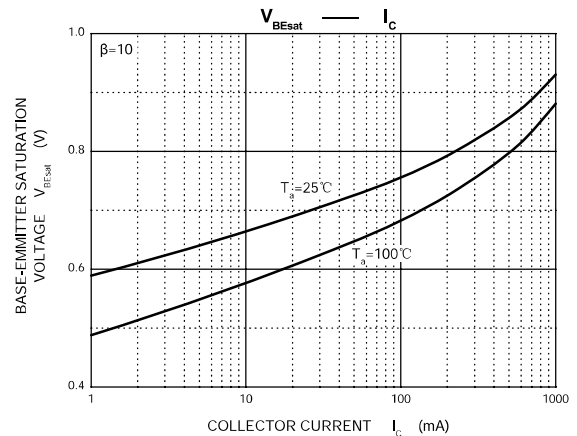
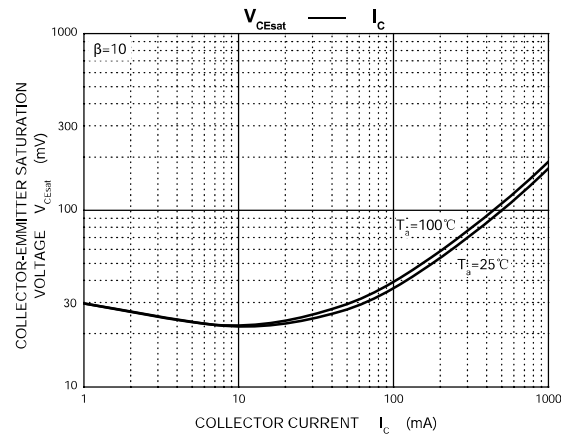
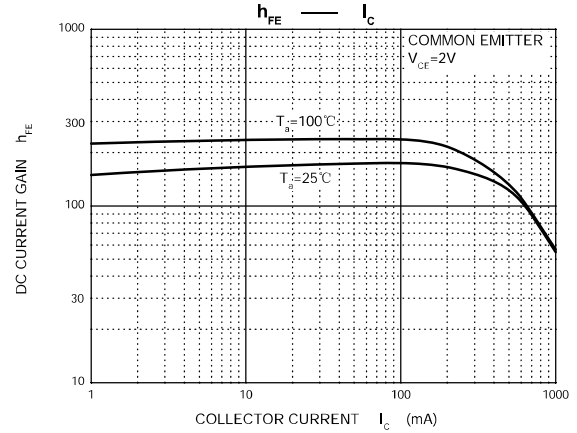
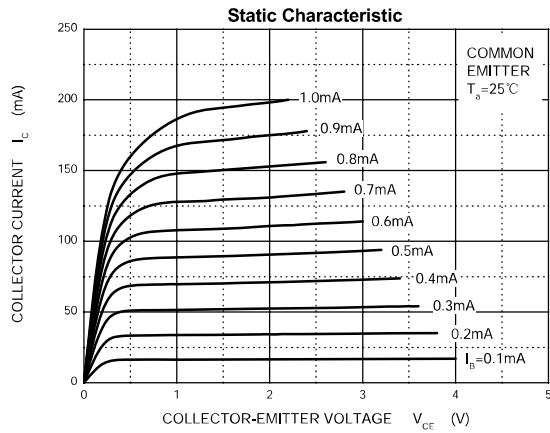
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C=100\mu A, I_E=0$	BCX54	45		V
			BCX55	60		
			BCX56	100		
Collector-emitter breakdown voltage	$V_{(BR)CEO}^*$	$I_C=10mA, I_B=0$	BCX54	45		V
			BCX55	60		
			BCX56	80		
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E=10\mu A, I_C=0$	5			V
Collector cut-off current	I_{CBO}	$V_{CB}=30V, I_E=0$			0.1	μA
Emitter cut-off current	I_{EBO}	$V_{EB}=5V, I_C=0$			0.1	μA
DC current gain	$h_{FE(1)}^*$	$V_{CE}=2V, I_C=5mA$	40			
	$h_{FE(2)}^*$	$V_{CE}=2V, I_C=150mA$	63		250	
	$h_{FE(3)}^*$	$V_{CE}=2V, I_C=0.5A$	25			
Collector-emitter saturation voltage	$V_{CE(sat)}^*$	$I_C=0.5A, I_B=50mA$			0.5	V
Base -emitter voltage	V_{BE}^*	$V_{CE}=2V, I_C=0.5A$			1	V
Transition frequency	f_T	$V_{CE}=5V, I_C=10mA, f=100MHz$		130		MHz

* Pulse Test

CLASSIFICATION OF $h_{FE(2)}$

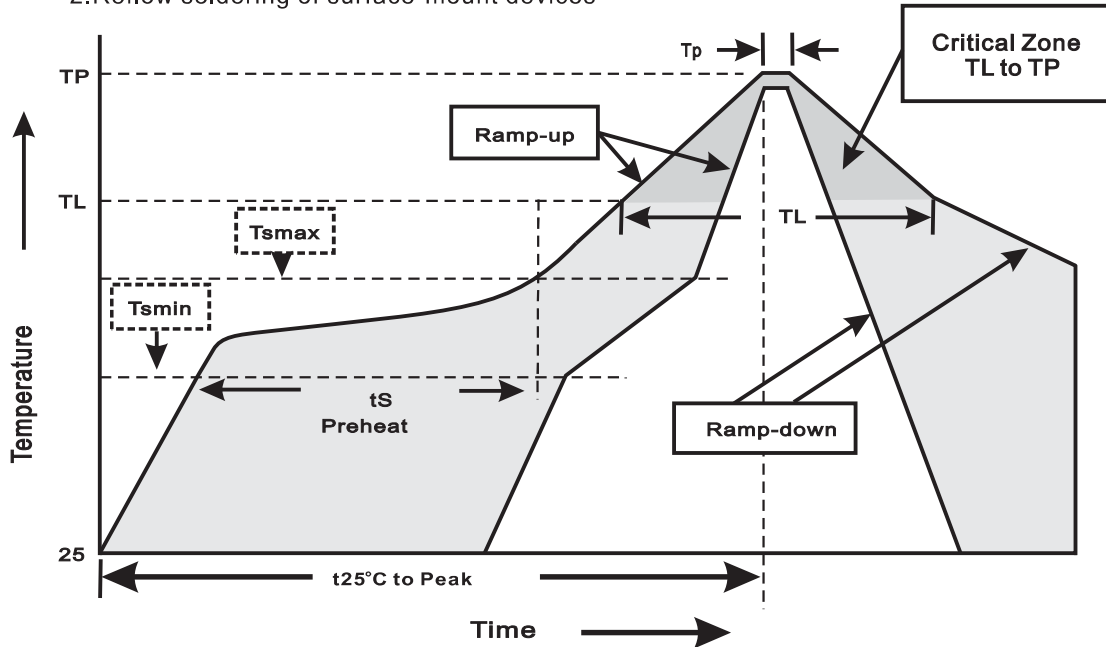
RANK	BCX54 BCX55 BCX56	BCX54-10 BCX55-10 BCX56-10	BCX54-16 BCX55-16 BCX56-16
RANGE	63 - 250	63 - 160	100 - 250

Rating and characteristic curves



Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes